SPECIFICATIONS FOR NICHIA CHIP TYPE WHITE LED MODEL : NSSW088T

NICHIA CORPORATION

1.SPECIFICATIONS

(1) Absolute Maximum Ratings

 $(Ta=25^{\circ}C)$

Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	IF	35	mA
Pulse Forward Current	IFP	100	mA
Allowable Reverse Current	Ir	85	mA
Power Dissipation	PD	123	mW
Operating Temperature	Topr	-40 ~ +110	°C
Storage Temperature	Tstg	-40 ~ +110	°C
Dice Temperature	Tj	125	°C
Soldering Temperature	Tsld	Reflow Soldering: 260°C fo	or 10sec.
		Hand Soldering : 350°C fe	or 3sec.

IFP Conditions : Pulse Width ≤ 10 msec. and Duty $\leq 1/10$

(2) Thermal Characteristics

 $(Ta=25^{\circ}C)$

Item	Symbol	Тур.	Unit
Heat resistance	Rja	380	°C/W
	Rjs	190	°C/W

^{*} Rja = Heat resistance from Dice to Ambient temperature (Ta)

Rjs = Heat resistance from Dice to Solder temperature of Cathode Side (Ts)

★ Using Nichia standard circuit board FR4, t=1.6mm, Copper foil, t=35µm

(3) Initial Electrical/Optical Characteristics

 $(Ta=25^{\circ}C)$

(14 20 c					/
Item	Symbol	Condition	Тур.	Max.	Unit
Forward Voltage	VF	IF=20[mA]	(3.2)	3.5	V
Luminous Intensity (Chromaticity Coordinate 1)	Iv	IF=20[mA]	(1500)	-	mcd
(Channel in the Constitute 1*)	-	IF=20[mA]	0.31	-	-
Chromaticity Coordinate 1	<i>7</i>	IF=20[mA]	0.32	-	-
Luminous Intensity (Chromaticity Coordinate 2)	Iv	IF=20[mA]	(1400)	-	mcd
Chromoticity Coordinate 2*	-	IF=20[mA]	0.28	-	-
Chromaticity Coordinate 2	-	IF=20[mA]	0.27	-	-

^{*} Please refer to CIE 1931 chromaticity diagram.

(4) Ranking

(Ta=25°C)

Item		Symbol	Condition	Min.	Max.	Unit
	Rank W1	Iv	IF=20[mA]	2000	2400	mcd
	Rank V2	Iv	IF=20[mA]	1720	2000	mcd
I umin ous Intensity	Rank V1	Iv	IF=20[mA]	1440	1720	mcd
Luminous Intensity	Rank U2	Iv	IF=20[mA]	1200	1440	mcd
	Rank U1	Iv	IF=20[mA]	1000	1200	mcd
	Rank T2	Iv	IF=20[mA]	860	1000	mcd

^{*} Luminous Intensity Measurement allowance is \pm 10%.

Color Ranks (IF=20mA,Ta=25°C)

	Rank a3				
X	0.280	0.264	0.287	0.296	
y	0.248	0.267	0.295	0.276	

	Rank b5				
X	0.296	0.287	0.307	0.311	
у	0.276	0.295	0.315	0.294	

	Rank b7				
X	0.291	0.279	0.302	0.308	
y	0.257	0.276	0.302	0.279	

	Rank b6				
X	0.311	0.307	0.330	0.330	
y	0.294	0.315	0.339	0.318	

	Rank b8				
X	0.308	0.302	0.319	0.321	
у	0.279	0.302	0.318	0.294	

^{*} Color Coordinates Measurement allowance is ± 0.01 .

2. INITIAL OPTICAL/ELECTRICAL CHARACTERISTICS

Please refer to figure's page.

3.OUTLINE DIMENSIONS AND MATERIALS

Please refer to figure's page.

Material as follows; Package : Heat-Resistant Polymer

Encapsulating Resin : Silicone Resin (with Diffused + Phosphor)

Electrodes : Ag Plating Copper Alloy

4.PACKAGING

· The LEDs are packed in cardboard boxes after taping.

Please refer to figure's page.

The label on the minimum packing unit shows; Part Number, Lot Number, Ranking, Quantity

- · In order to protect the LEDs from mechanical shock, we pack them in cardboard boxes for transportation.
- The LEDs may be damaged if the boxes are dropped or receive a strong impact against them, so precautions must be taken to prevent any damage.
- · The boxes are not water resistant and therefore must be kept away from water and moisture.
- · When the LEDs are transported, we recommend that you use the same packing method as Nichia.

5.LOT NUMBER

The first six digits number shows **lot number**.

The lot number is composed of the following characters;

 $\bigcirc \square \times \times \times \times$ - $\triangle \blacksquare$

O - Year (6 for 2006, 7 for 2007)

□ - Month (1 for Jan., 9 for Sep., A for Oct., B for Nov.)

×××× - Nichia's Product Number

 \triangle - Ranking by Color Coordinates

Ranking by Luminous Intensity

^{*} One delivery will include one set of the above color ranks (a3 or b5 and b6 or b7 and b8) and six luminous intensity ranks of the products. The quantity-ratio of the ranks is decided by Nichia.

6.RELIABILITY

(1) TEST ITEMS AND RESULTS

	Standard			Number of
Test Item	Test Method	Test Conditions	Note	Damaged
Resistance to	JEITA ED-4701	Tsld=260°C, 10sec.	2 times	0/22
Soldering Heat	300 301	(Pre treatment 30°C,70%,168hrs.)		
(Reflow Soldering)	TELET ED 4701	T 11 215 50G 2	1	0./22
Solderability (P. St. 11 i.)	JEITA ED-4701	$Tsld=215 \pm 5$ °C, 3sec.	1 time	0/22
(Reflow Soldering)	300 303	(using flux, Lead Solder)	over 95%	
Thermal Shock	JEITA ED-4701	-40°C ~ 110°C	100 cycles	0/100
	300 307	1min. (10sec.) 1min. (Pre treatment 30°C,70%,168hrs.)		
Temperature Cycle	JEITA ED-4701	-40°C ~ 25°C ~ 110°C ~ 25°C	100 cycles	0/100
	100 105	30min. 5min. 30min. 5min.		
Moisture Resistance Cyclic	JEITA ED-4701	25°C ~ 65°C ~ -10°C	10 cycles	0/100
	200 203	90%RH 24hrs./1cycle		
High Temperature Storage	JEITA ED-4701	Ta=110°C	1000 hrs.	0/100
	200 201			
Temperature Humidity	JEITA ED-4701	Ta=60°C, RH=90%	1000 hrs.	0/100
Storage	100 103			
Low Temperature Storage	JEITA ED-4701	Ta=-40°C	1000 hrs.	0/100
	200 202			
Steady State Operating Life **		Ta=25°C, IF=35mA	1000 hrs.	0/100
Steady State Operating Life of High Temperature **		Ta=85°C, IF=25mA	1000 hrs.	0/100
Steady State Operating Life		60°C, RH=90%, IF=20mA	1000 hrs.	0/100
of High Humidity Heat **		,		
Steady State Operating Life		Ta=-40°C, IF=20mA	1000 hrs.	0/100
of Low Temperature **		,		
Permanence of Marking	JEITA ED-4701	Solvent : Isopropyl Alcohol	1 time	0/22
S	500 501	Solvent Temperature : 20 ~ 25°C		
		Dipping Time : 5 min.		
Vibration	JEITA ED-4701	100 ~ 2000 ~ 100Hz Sweep 4min.	48min.	0/10
	400 403	200m/s^2		
		3directions, 4cycles		
Drop		75cm	3 times	0/10
Electrostatic Discharge	JEITA ED-4701	R=1.5kΩ, C=100pF	3 times	0/22
	300 304	Test Voltage=2kV	Negative/Positive	

(2) CRITERIA FOR JUDGING DAMAGE

			Criteria for Judgement		
Item	Symbol	Test Conditions	Min.	Max.	
Forward Voltage	VF	IF=20mA	-	U.S.L.*)× 1.1	
Luminous Intensity Condition 1	Iv	IF=20mA	L.S.L.**)× 0.7	-	
Luminous Intensity Condition 2 **	Iv	IF=20mA	L.S.L.**)× 0.5	-	

^{*)} U.S.L.: Upper Standard Level

^{**)} L.S.L.: Lower Standard Level

^{**} These test items are judged by the criteria of Luminous Intensity Condition 2.

7.CAUTIONS

The LEDs are devices which are materialized by combining Blue LEDs and special phosphors. Consequently, the color of the LEDs is changed a little by an operating current. Care should be taken after due consideration when using LEDs.

(1) Moisture Proof Package

- · When moisture is absorbed into the SMT package it may vaporize and expand during soldering. There is a possibility that this can cause exfoliation of the contacts and damage to the optical characteristics of the LEDs. For this reason, the moisture proof package is used to keep moisture to a minimum in the package.
- The moisture proof package is made of an aluminum moisture proof bag. A package of a moisture absorbent material (silica gel) is inserted into the aluminum moisture proof bag. The silica gel changes its color from blue to pink as it absorbs moisture.

(2) Storage

· Storage Conditions

Before opening the package:

The LEDs should be kept at 30°C or less and 90%RH or less. The LEDs should be used within a year. When storing the LEDs, moisture proof packaging with absorbent material (silica gel) is recommended.

After opening the package:

The LEDs should be kept at 30°C or less and 70%RH or less. The LEDs should be soldered within 168 hours (7days) after opening the package. If unused LEDs remain, they should be stored in moisture proof packages, such as sealed containers with packages of moisture absorbent material (silica gel). It is also recommended to return the LEDs to the original moisture proof bag and to reseal the moisture proof bag again.

· If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : more than 24 hours at $65 \pm 5^{\circ}$ C

- · Nichia LED electrodes and leadframes are silver plated copper alloy. The silver surface may be affected by environments which contain corrosive substances. Please avoid conditions which may cause the LED to corrode, tarnish or discolor. This corrosion or discoloration might lower solderability or might affect on optical characteristics.
- · Please avoid rapid transitions in ambient temperature, especially in high humidity environments where condensation can occur.

(3) Heat Generation

- Thermal design of the end product is of paramount importance. Please consider the heat generation of the LED when making the system design. The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board, as well as other components. It is necessary to avoid intense heat generation and operate within the maximum ratings given in this specification.
- The operating current should be decided after considering the ambient maximum temperature of LEDs.

(4) Soldering Conditions

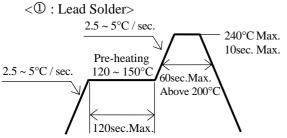
• The LEDs can be soldered in place using the reflow soldering method. Nichia cannot make a guarantee on the LEDs after they have been assembled using the dip soldering method.

· Recommended soldering conditions

Reflow Soldering			Hand Soldering	
	Lead Solder	Lead-free Solder		
Pre-heat	120 ~ 150°C	180 ~ 200°C	Temperature	350°C Max.
Pre-heat time	120 sec. Max.	120 sec. Max.	Soldering time	3 sec. Max.
Peak	240°C Max.	260°C Max.		(one time only)
temperature				
Soldering time	10 sec. Max.	10 sec. Max.		
Condition	refer to	refer to		
	Temperature	Temperature		
	- profile ①.	- profile ②.		
		$(N_2 \text{ reflow is})$		
		recommended.)		

- * Although the recommended soldering conditions are specified in the above table, reflow or hand soldering at the lowest possible temperature is desirable for the LEDs.
- * A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature. [Temperature-profile (Surface of circuit board)]

Use the conditions shown to the under figure.



<2 : Lead-free Solder>

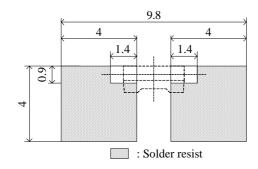
1~5°C / sec.

Pre-heating
180 ~ 200°C
60sec.Max.
Above 220°C

120sec.Max.

[Recommended soldering pad design]

Use the following conditions shown in the figure.



(Unit: mm)

- · Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- · Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- · Reflow soldering should not be done more than two times.
- · When soldering, do not put stress on the LEDs during heating.
- · After soldering, do not warp the circuit board.

(5) Cleaning

- · It is recommended that isopropyl alcohol be used as a solvent for cleaning the LEDs. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not. Freon solvents should not be used to clean the LEDs because of worldwide regulations.
- · Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power and the assembled condition. Before cleaning, a pre-test should be done to confirm whether any damage to the LEDs will occur.

(6) Static Electricity

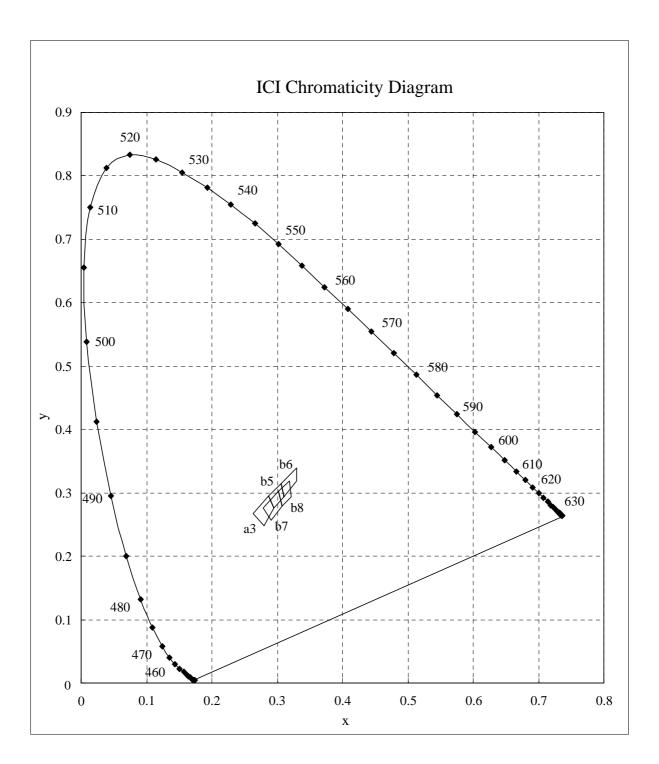
- · Static electricity or surge voltage damages the LEDs.

 It is recommended that a wrist band or an anti-electrostatic glove be used when handling the LEDs.
- · All devices, equipment and machinery must be properly grounded. It is recommended that precautions be taken against surge voltage to the equipment that mounts the LEDs.
- · When inspecting the final products in which LEDs were assembled, it is recommended to check whether the assembled LEDs are damaged by static electricity or not. It is easy to find static-damaged LEDs by a light-on test or a VF test at a lower current (below 1mA is recommended).
- · Damaged LEDs will show some unusual characteristics such as the forward voltage becomes lower, or the LEDs do not light at the low current.

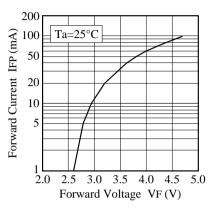
Criteria: (VF > 2.0V at IF=0.5mA)

(7) Others

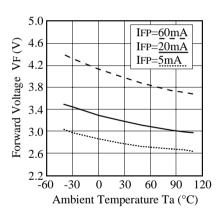
- · NSSW088 complies with RoHS Directive.
- The LED light output is strong enough to injure human eyes. Precautions must be taken to prevent looking directly at the LEDs with unaided eyes for more than a few seconds.
- · Flashing lights have been known to cause discomfort in people; you can prevent this by taking precautions during use. Also, people should be cautious when using equipment that has had LEDs incorporated into it.
- The LEDs described in this brochure are intended to be used for ordinary electronic equipment (such as office equipment, communications equipment, measurement instruments and household appliances). Consult Nichia's sales staff in advance for information on the applications in which exceptional quality and reliability are required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as for airplanes, aerospace, submersible repeaters, nuclear reactor control systems, automobiles, traffic control equipment, life support systems and safety devices).
- · User shall not reverse engineer by disassembling or analysis of the LEDs without having prior written consent from Nichia. When defective LEDs are found, the User shall inform Nichia directly before disassembling or analysis.
- · The formal specifications must be exchanged and signed by both parties before large volume purchase begins.
- The appearance and specifications of the product may be modified for improvement without notice.



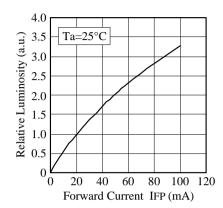
* Color Coordinates Measurement allowance is ± 0.01 .



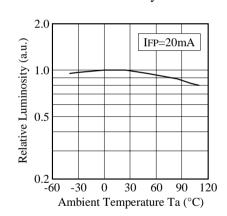
■ Ambient Temperature vs. Forward Voltage



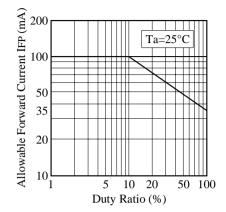
■ Forward Current vs. Relative Luminosity



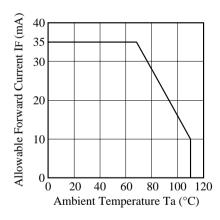
■ Ambient Temperature vs. Relative Luminosity



Duty Ratio vs.Allowable Forward Current



■ Ambient Temperature vs. Allowable Forward Current



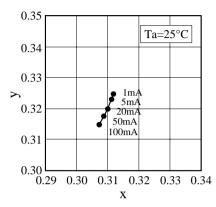
NICHIA CORPORATION

Model	NSSW088	\setminus
Title	CHARACTERISTICS	
No.	070306761801	
	Title	Title CHARACTERISTICS

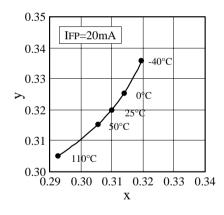
Nichia

STSE-CC7027A <Cat.No.070309>

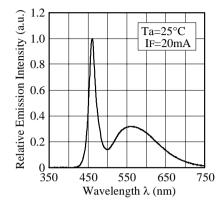
■ Forward Current vs. Chromaticity Coordinate



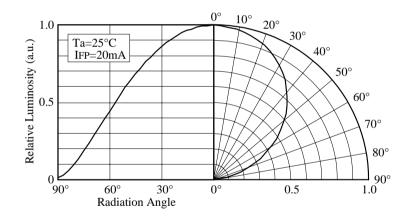
■ Ambient Temperature vs. Chromaticity Coordinate



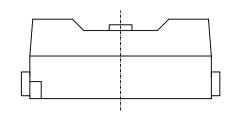
■ Spectrum

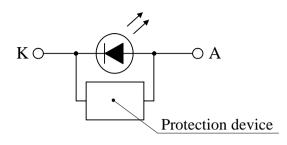


■ Directivity

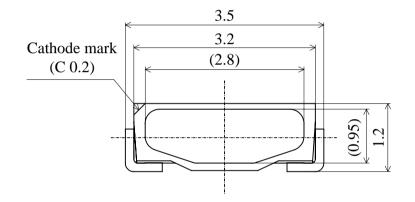


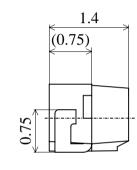
	Model	NSSW088	V
1	Title	CHARACTERISTICS	
	No.	070306761811	

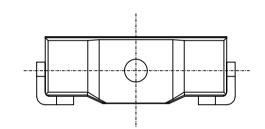


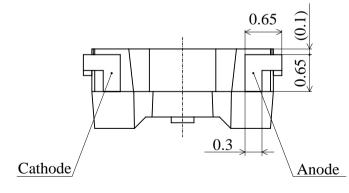


Internal Circuit







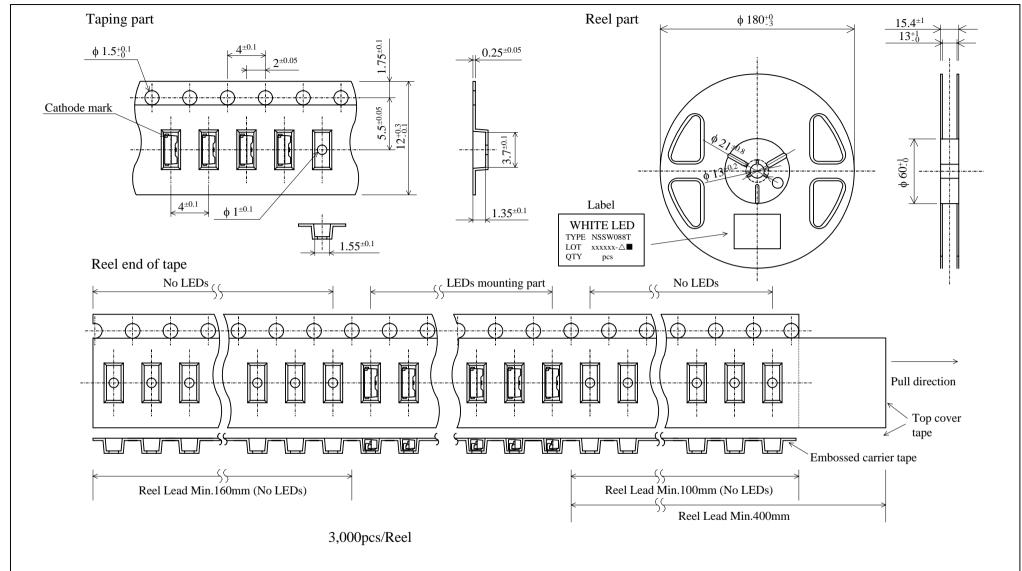


ITEM	MATERIALS
PACKAGE	Heat-Resistant Polymer
ENCAPSULATING RESIN	Silicone Resin (with Diffused + Phosphor)
ELECTRODES	Ag Plating Copper Alloy

Note 1) NSSW088 has a protection device built in as a protection
circuit against static electricity.

Note 2) The LED may have flash/flange which exceeds the tolerance of this print.

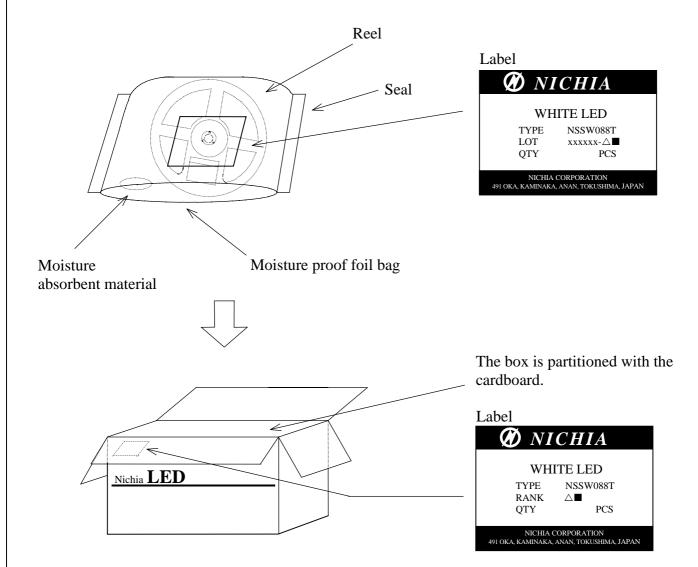
	Model	NSSW088	Unit
NICHIA CORPORATION	Title	OUTLINE DIMENSIONS	15/1 Scale
	No.	070302761821	Allow +0.1



Taping is based on the **JIS C 0806**: Packaging of Electronic Components on Continuous Tapes.

	Model	NSSW088T	Unit Cat.
NICHIA CORPORATION	Title	TAPING DIMENSIONS	Scale Scale
	No.	070306761831	Allow 309>

The reel and moisture absorbent material are put in the moisture proof foil bag and then heat sealed.



Packing unit

	Reel/bag	Quantity/bag (pcs)
Moisture proof foil bag	1reel	3,000 MAX.

Cardboard box	Dimensions (mm)	Reel/box	Quantity/box (pcs)
Cardboard box S	291×237×120×8t	5reel MAX.	15,000 MAX.
Cardboard box M	259×247×243×5t	10reel MAX.	30,000 MAX.
Cardboard box L	444×262×259×8t	20reel MAX.	60,000 MAX.

	Model	NSSW088T	
NICHIA CORPORATION	Title	PACKING	
	No.	070305761841	